Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	49	("6157452" "5601957" "6110021" "4500615" "5455679" "5733711" "6154281" "20040227945" "5328807" "6171736" "6180289" "6204509" "5285258" "5570405" "5796483" "5859707" "5985495" "5596413" "4777641" "4801808" "4857742" "4881100" "4971444" "5000573" "5200800" "5225892" "5227838" "5262257" "5377009" "5396335" "5483348" "5495336" "5521036" "5572325" "5726758" "5882980" "5917205" "6018384" "6236448" "4590382" "4617469" "4629313" "4770533" "4771180" "4780615" "4794648" "4795244" "4803524" "4865455" "4871257").pn.	USPAT	OR	OFF	2006/08/30 13:23
S2	49	("6157452" "5601957" "6110021" "4500615" "5455679" "5733711" "6154281" "20040227945" "5328807" "6171736" "6180289" "6204509" "5285258" "5570405" "5796483" "5859707" "5985495" "5596413" "4777641" "4801808" "4857742" "4881100" "4971444" "5000573" "5200800" "5225892" "5227838" "5262257" "5377009" "5396335" "5483348" "5495336" "5521036" "5572325" "5726758" "5882980" "5917205" "6018384" "6236448" "4590382" "4617469" "4629313" "4770533" "4771180" "4780615" "4794648" "4795244" "4803524" "4865455" "4871257").pn.	USPAT	OR	OFF	2006/08/15 14:29
S3	2202902	S2 and alignment marks and exposure surface	USPAT	OR	OFF	2006/08/15 14:31
S4	4	S2 and scattering	USPAT	OR	OFF	2006/08/15 14:31
S5	556	257/797.ccls.	USPAT; USOCR	AND	OFF	2006/09/05 14:50
S6	353	S5 and wafer	USPAT; USOCR	AND	OFF	2006/08/28 07:43
S7	204	S6 and alignment marks	USPAT; USOCR	AND	OFF	2006/08/28 08:00

S14	19	("5316966" "5668042" "5733801" "5893744" "5949145" "6015744" "6037671" "6043133" "6100158" "6181018"	US-PGPUB; USPAT; USOCR	AND	OFF	2006/08/28 08:24
		"6191000" "6215197" "6285455" "6326309" "6342735" "6344698" "6391737" "6440816" "6545336").PN.				
S15	4.	("5601957" "5917604" "6255189" "6285455").PN.	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/28 09:18
S16		("4704027" "5329334" "5503962" "5786260" "5911108" "5923996" "5981352" "6037671" "6049137" "6083807" "6235437" "6249036" "6274940" "6342735" "6388341" "6479904").PN.	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/28 10:49
S17.	16879	(wafer OR vernier OR substrate OR chip OR film OR structure OR pad OR conductive member) NEAR (dot patterns OR reference array OR embedded portions OR recess part OR spacing OR trench OR overlay mark)	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/09/05 11:36
S18	42	S17 with alignment mark	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/28 16:07
S19	46	S17 with interval	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/28 15:52
S20	25	S17 with (interval NOT constant)	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/28 15:53
S21	1	("5525840"):PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/08/30 08:16
S22	536	S17 WITH ((interval OR period OR seperation OR gap OR space OR division) NOT constant)	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/28 16:14
S23	84	S22 SAME semiconductor	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/28 16:14
S24	344	S17 WITH ((interval OR period OR seperation OR space OR division) NOT constant)	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/28 16:14

S25	50	S24 SAME semiconductor	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/28 16:14
S26	38	("4893163" "4981529" "5405810").PN. OR ("5525840"). URPN.	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/28 16:30
S27	1	(" 444 1250").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/08/28 16:31
S28	18	("3802940" "3928094" "4037161" "4070117" "4187431" "4200395" "4211489" "4232969" "4377028").PN. OR ("4441250"). URPN.	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/28 16:40
S29	4188	exposure adj mask	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/28 16:41
S30	10	S29 NEAR alignment mark	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/28 16:42
S31	· 7	"exposure mask" NEAR (dot patterns OR reference array OR embedded portions OR recess part OR spacing OR trench OR overlay mark)	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/28 16:43
S32	70	reticle NEAR (dot patterns OR reference array OR embedded portions OR recess part OR spacing OR trench OR overlay mark)	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/29 14:31
S33	1	("6810104").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/08/29 15:11
S34	1	("6963390").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/08/29 15:11
S35	237	yamaguchi and reticle	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/30 07:49
S36	11901	yamaguchi:in.	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/30 07:50
S37	5	"246717".ap.	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/30 07:50

S38	0	"raised OR grooved" NEAR (dot patterns OR reference array OR embedded portions OR recess part OR spacing OR trenches OR overlay mask)	IBM_TDB	NEAR	OFF	2006/08/30 08:18
S39	0	"raised OR grooved" SAME (dot patterns OR reference array OR embedded portions OR recess part OR spacing OR trenches OR overlay mask)	.IBM_TDB	NEAR	OFF	2006/08/30 08:18
S40	16895	(wafer OR vernier OR substrate OR chip OR film OR structure OR pad OR conductive member) NEAR (dot patterns OR reference array OR embedded portions OR recess part OR spacing OR trench OR overlay mark)	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/30 08:18
S41	0	"raised OR grooved" NEAR S40	IBM_TDB	NEAR	OFF	2006/08/30 08:18
S42	3	("4893163" "4981529" "5405810").PN.	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/31 11:17
S43	1	("4636077"):PN:	US-PGPUB; USPAT; USOCR	OR	OFF	2006/08/31 14:53
S44	1	("4650983").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/08/31 12:49
S45	16913	(wafer OR vernier OR substrate OR chip OR film OR structure OR pad OR conductive member) NEAR (dot patterns OR reference array OR embedded portions OR recess part OR spacing OR trench OR overlay mark)	US-PGPUB; USPAT; USOCR	NEAR	OFF	2007/04/04 10:43
S46	14535	S45 and method	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/08/31 14:56
S47	1327	S46 AND incident	US-PGPUB; USPAT; USOCR	ADJ	OFF	2006/08/31 14:57
S48	44	S46 AND (incident with oblique)	US-PGPUB; USPAT; USOCR	ADJ	OFF	2006/08/31 15:01
S49	222	S46 AND (incident SAME (oblique OR slanted OR indirect OR "at an angle" OR perpendicular))	US-PGPUB; USPAT; USOCR	ADJ	OFF	2006/09/05 14:53

S50	71	S49 AND exposure	US-PGPUB; USPAT; USOCR	ADJ	OFF	2006/08/31 15:03
S51	922	(wafer OR vernier OR substrate OR chip OR film OR structure OR pad OR conductive member) NEAR (dot patterns OR reference array OR embedded portions OR recess part OR spacing OR trench OR overlay mark) AND (method WITH alignment)	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/09/05:11:39
S52	141	S51 AND incident	US-PGPUB; USPAT; USOCR	NEAR	OFF	2006/09/05 11:39
S53	0	("2005/0285283").URPN.	USPAT	NEAR	OFF	2006/09/05 14:39
S54	560	257/797.ccls.	USPAT; USOCR	AND	OFF	2006/09/05 14:50
S55	508	S54 AND method	USPAT; USOCR	AND	OFF	2006/09/05 14:53
S56	13	S55 AND (incident SAME (oblique OR slanted OR indirect OR "at an angle" OR perpendicular))	US-PGPUB; USPAT; USOCR	ADJ	OFF	2006/09/05 14:54
S57	14	(wafer OR vernier OR substrate OR chip OR film OR structure OR pad OR conductive member) NEAR (dot patterns OR reference array OR spacing OR mark) NEAR raised	US-PGPUB; USPAT; USOCR	NEAR	OFF	2007/04/04 10:45
S58	592	257/797.ccls.	USPAT; USOCR	AND	OFF	2007/04/04 10:47
S59	. 2154	S58 OR 356/401.ccls. OR 356/602.ccls.	US-PGPUB; USPAT; USOCR	NEAR	OFF	2007/04/04 10:47
S60	150	S59 AND raised	US-PGPUB; USPAT; USOCR	NEAR	OFF	2007/04/04 11:08
S61	2	("5369050"):PN.	US-PGPUB; USPAT; USOCR; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/04 13:40
S62	1474	(356/401).CCLS.	US-PGPUB; USPAT; USOCR; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/04 13:40

S63	570	S62 AND (convex OR raised OR project OR protrude OR elevate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2007/04/04 13:52
S64	240	S62 AND (convex OR raised OR protrude OR elevate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2007/04/04 14:04
S65	550	((align\$4 same (negative same positive)) same photoresist) and pattern\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2007/04/04 14:08
S66	7	((align\$4 same (negative same positive)) same photoresist) and ((dot hole) same pattern\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	AND	ON	2007/04/04:14:08

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